Form PTO-1595

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To the Honorable Commissioner of .

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ER SHEET U.S. Department of Commerce Pateni and Trademark Office

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one are exached original documents or copy thereof

	 Name of conveying party(ies): 	2. Name and address of receiving party(ies):
	John T. Moore	Name: Micron Technology, Inc.
:	Additional name(s) of conveying Yes party(ies) attached? X No	Internal Address:
-	3. Nature of Conveyance:	J. C. S. C.
	x Assignment Merger	City: Boise
	Security Agreement Change of Name	State: ID Zip: 83706-9632
	Other	Country: USA
	Execution Date(s): 2/9/00	Additional name(s) & Session S
	4. Application number(s) or patent number(s):	
	If this document is being filed together with a new application, the Execution date(s) of the new application is (are):	
	A. Patent Application No.(s):	B. Patent No.(s):
		Additional numbers attached? Yes X No
	Name and address of party to whom correspondence concerning document should be mailed:	e 6. Total number of applications and 1 patents involved:
	Name: DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP	7. Total fee (37 C.F.R 3.41) \$ \$40.00
:	Internal Address: Atty. Dkt.: M4065.0253/P253	x Enclosed
03/02/2000 PS 04 FC:581	Attn: Thomas J. D'Amico	Authorized to be charged to deposit account
	Street Address: (2101 Street NW	x Credit any overpayment condebit any underpayment
	City:State:Zip:WashingtonDC20037 - 1526	8. Deposit account number: 4 - 073
	DO NOT USE THIS SPACE	
	Statement and signature.	
	To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.	
	Thomas J. D'Amico	February 22, 2000
i	Signature	Date
	Reg. No. 28,371	
į	Total number of pages including cover sheet, attachments, and document: 3	

Docket No.: M4065.0253/P253 Micron No.: 98-0800.00/US

ASSIGNMENT AND AGREEMENT

For value received, I, John T. Moore, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled METHOD OF FORMING LOW DIELECTRIC SILICON **OXYNITRIDE** SPACER **FILMS** HIGHLY SELECTIVE TO ETCHANTS, described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

1107676 v1; NQ_S01!.DOC

PATENT REEL: 010581 FRAME: 0317

Docket No.: M4065.1)253/P253 Micron No.: 98-0800.00/US

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Date: 2 - 9 - 00	John T. Moore		
United States of America State of))ss.:		
County of Ada			
On this 9 day of	Sebruary, , before me		
personally came John T. Moore	, to me known to be the		
ndividual described in and who executed	d the foregoing instrument, and acknowledged		
execution of the same.			
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RECORDED: 02/22/2000

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PATENT REEL: 010581 FRAME: 0318